

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	29550	silicon near4 ((aluminum adj oxide) (boron adj nitride))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:03
L2	75	1 with (encapsulant encapsulated encapsulating (sealing near resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:24

L13	232	(US-20040046241-\$ or US-20050036291-\$).did. or (US-4092697-\$ or US-4561011-\$ or US-4612601-\$ or US-4628990-\$ or US-4654966-\$ or US-4744007-\$ or US-4949219-\$ or US-5067007-\$ or US-5108955-\$ or US-5126829-\$ or US-5151773-\$ or US-5153379-\$ or US-5168348-\$ or US-5175612-\$ or US-5175613-\$ or US-5227663-\$ or US-5276289-\$ or US-5276586-\$ or US-5306948-\$ or US-5311402-\$ or US-5329160-\$ or US-5345107-\$ or US-5349831-\$ or US-5365107-\$ or US-5371404-\$ or US-5396403-\$).did. or (US-5430611-\$ or US-5455457-\$ or US-5468910-\$ or US-5471027-\$ or US-5476818-\$ or US-5477082-\$ or US-5510956-\$ or US-5587882-\$ or US-5594282-\$ or US-5604978-\$ or US-5616957-\$ or US-5619070-\$ or US-5623394-\$ or US-5650918-\$ or US-5655290-\$ or US-5705850-\$ or US-5705851-\$ or US-5724729-\$ or US-5726079-\$ or US-5736785-\$ or US-5739581-\$ or US-5744752-\$ or US-5745344-\$ or US-5751062-\$ or US-5757620-\$ or US-5777847-\$ or US-5789813-\$).did. or (US-5811317-\$ or US-5819402-\$ or US-5834327-\$ or US-5844311-\$ or US-5881944-\$ or US-5881945-\$ or US-5883425-\$ or US-5883430-\$ or US-5889323-\$ or US-5891753-\$ or US-5898224-\$ or US-5904497-\$ or US-5905636-\$ or US-5907474-\$ or US-5909056-\$ or US-5909057-\$ or US-5920120-\$ or US-5926371-\$ or US-5931222-\$ or US-5940271-\$ or US-5950073-\$ or US-5956576-\$ or US-5969426-\$ or US-5977626-\$ or US-5981310-\$ or US-5982038-\$ or US-5982621-\$).did. or (US-5990418-\$ or US-6008536-\$ or US-6023096-\$ or US-6025995-\$ or US-6046077-\$ or US-6046498-\$ or US-6051888-\$ or US-6064217-\$ or US-6081037-\$ or US-6082443-\$ or US-6091603-\$ or US-6104093-\$ or US-6111322-\$ or US-6114761-\$ or US-6121680-\$ or US-6124636-\$ or US-6140707-\$ or US-6144101-\$ or US-6146921-\$ or US-6163458-\$ or US-6165820-\$ or US-6166435-\$ or US-6184580-\$ or US-6190945-\$	US-PGPUB; USPAT	OR	ON	2005/04/23 08:04
Search History	4/23/05 8:54:19 AM 60 Page US-6206997-\$ C:\Documents and Settings\UST6208919\My Documents\FAST\Workspaces\%Heat-sink-attach-to-surface-of-chip.wsp (US-6214647-\$ or US-6215180-\$					

L14	0	2 and "w/m.k."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:20
L15	0	2 and "1.5w/m.k."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:05
L16	2	2 with (thermal adj conductivity)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:05
L17	5	2 same (thermal adj conductivity)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:14
L18	12	2 and (thermal near1 conductivity)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:15
L19	1	"w/m.k."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:20
L20	0	"1.5w/m.k."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:20
L21	0	"1.5 w/m.k."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:21
L22	0	"1.5W/m.K."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:21
L23	1	"W/m.K."	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:22
L24	831	"W/m.K"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/04/23 08:22
L25	3	24 with (thermal near1 conductivity) with (encapsulant encapsulated encapsulating (sealing near resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:24
L26	603	24 with (thermal near1 conductivity)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:24
L27	3	26 same (encapsulant encapsulated encapsulating (sealing near resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:24
L28	26	26 and (encapsulant encapsulated encapsulating (sealing near resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/04/23 08:24